

Radiation-Hardened Point-of-Load Power Conversion

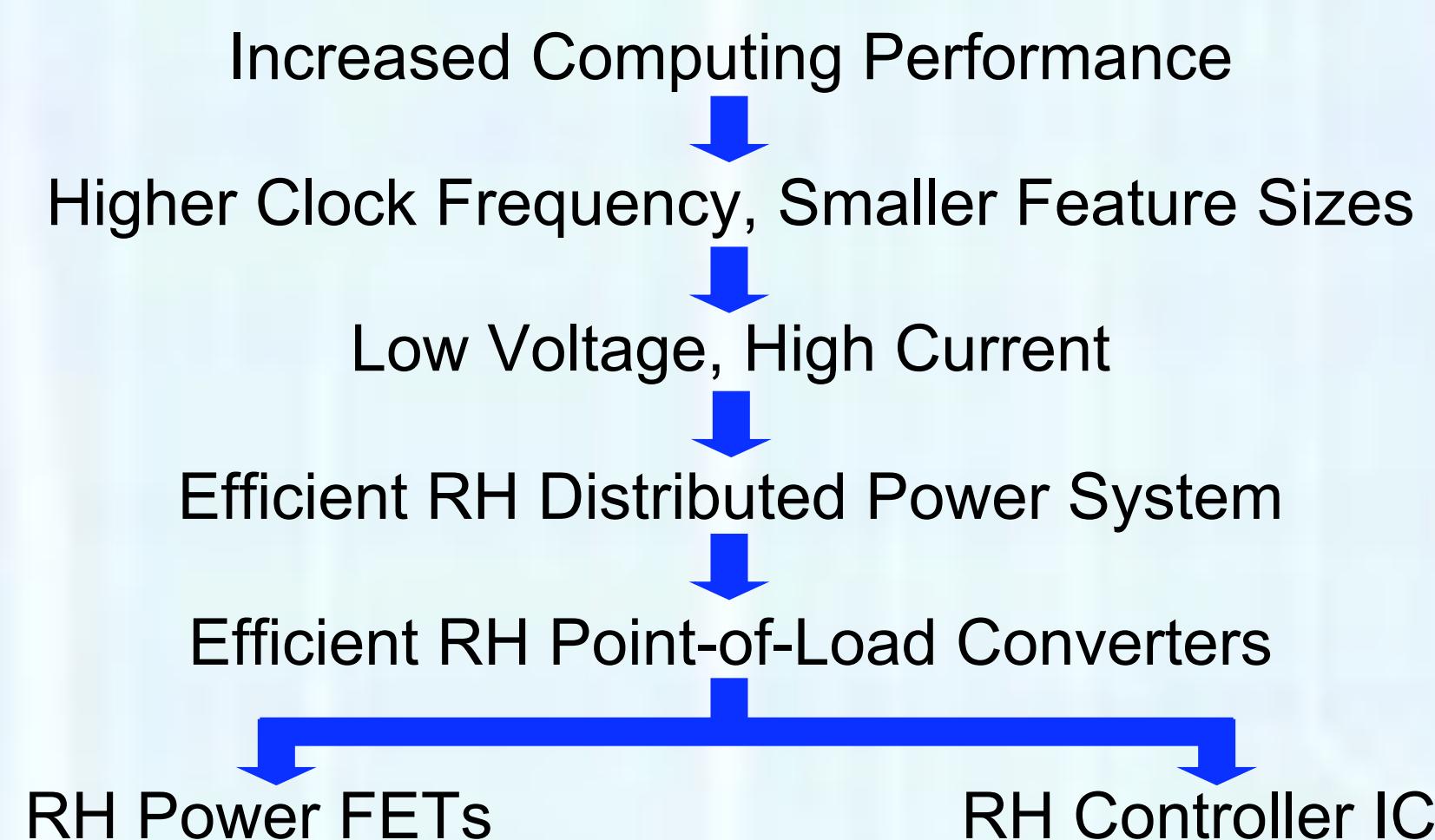


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Problem

Powering Digital Systems in High-rad Environments



Objective - Develop radiation-hardened power MOSFET and HVCmos technologies that enable an order-of-magnitude improvement in the size and efficiency of point-of-load converters for processor applications high radiation environments.

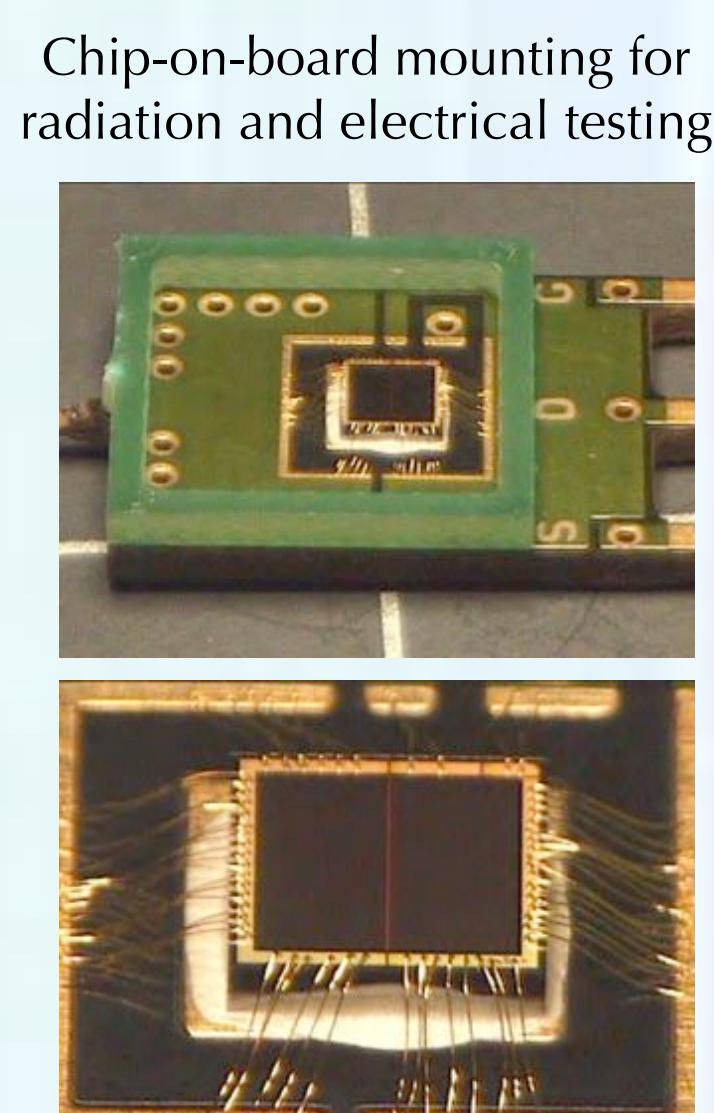
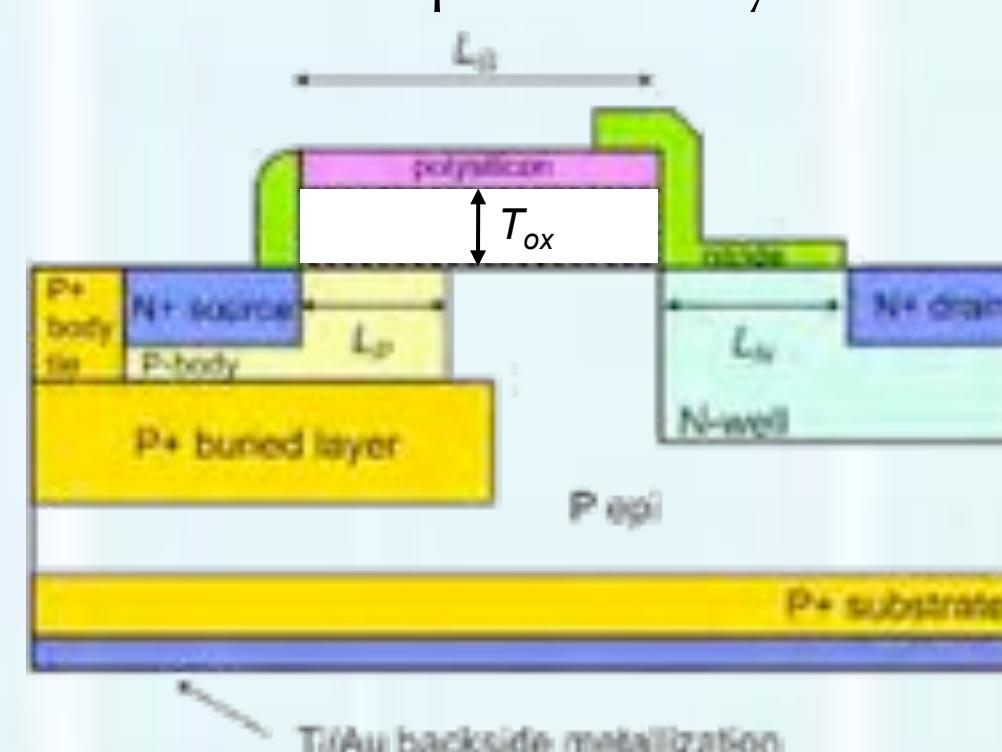
Primary Requirements

- Total dose tolerant to > 100 kRad
- Latch-up Immune
- No SEE to LET > 80 MeV·cm²/mg
- Switching frequency > 300 kHz
- Target efficiency > 90%

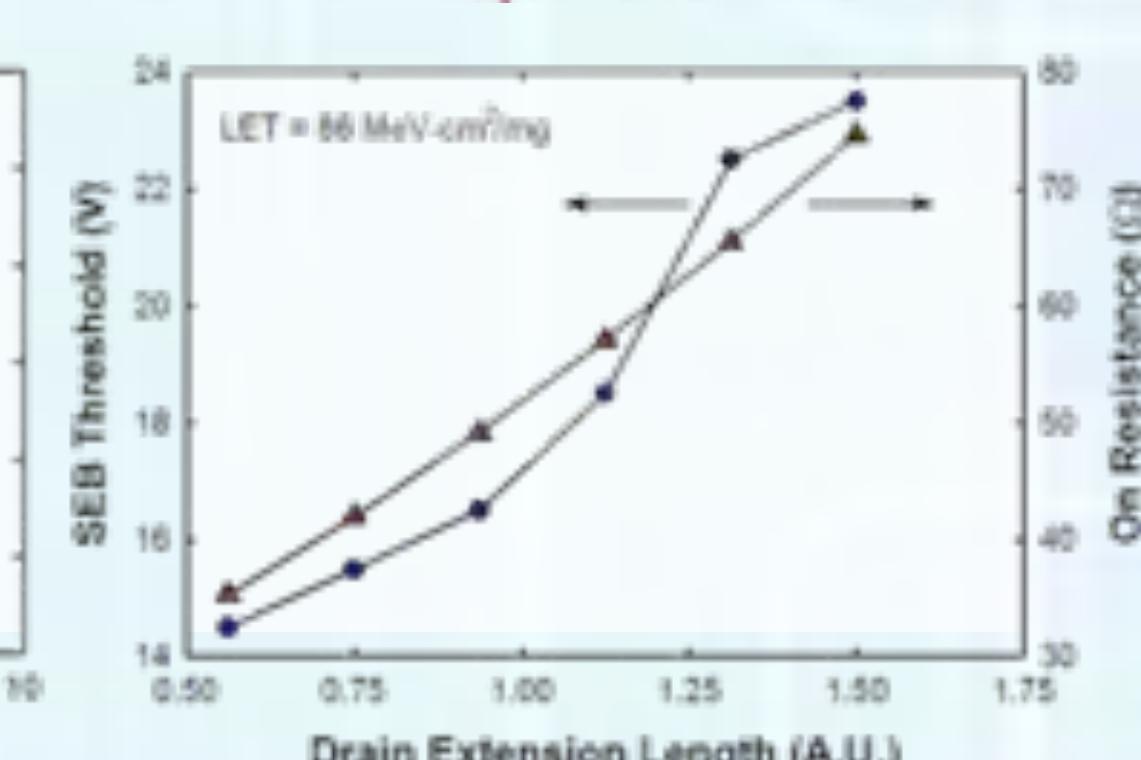
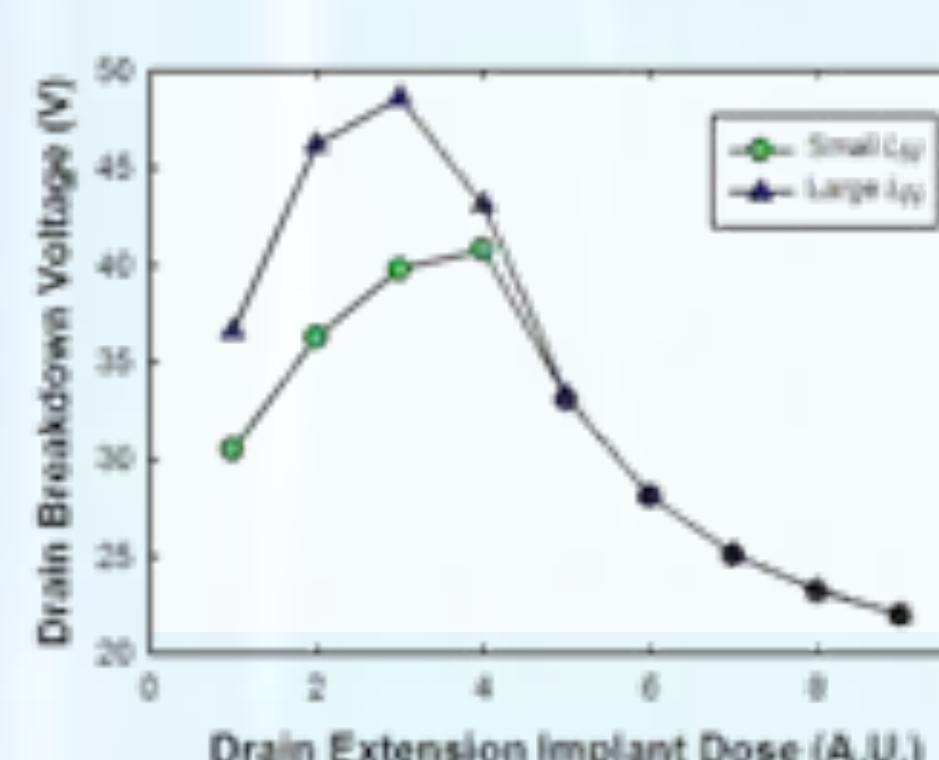
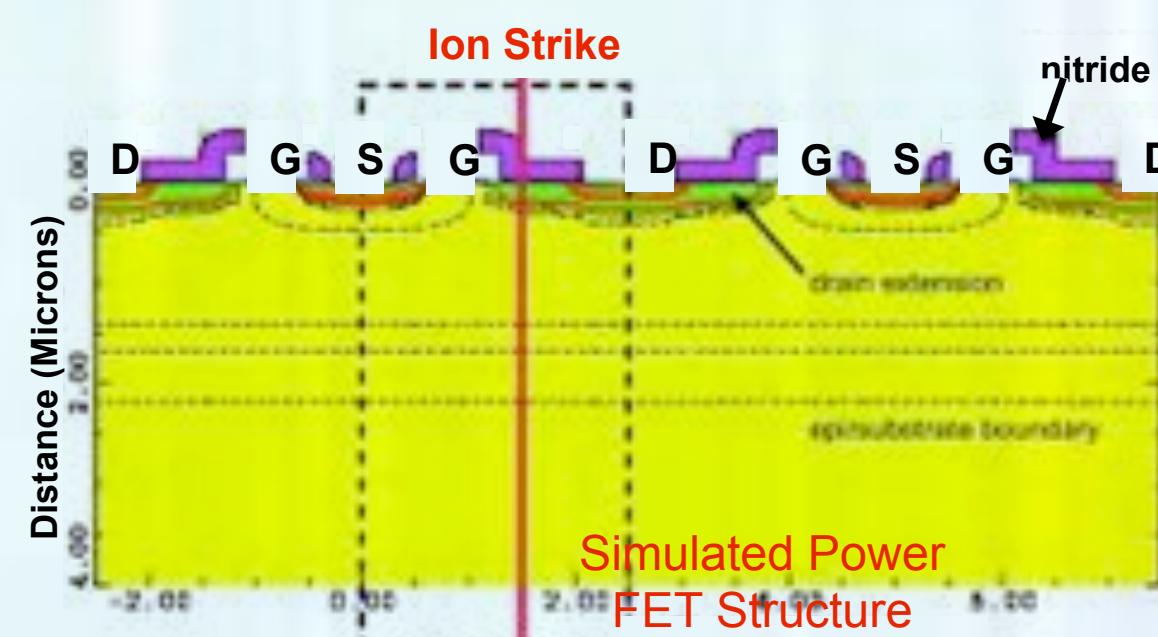
Approach

Rad-Hard Power FET

3rd Iteration design with improved body tie

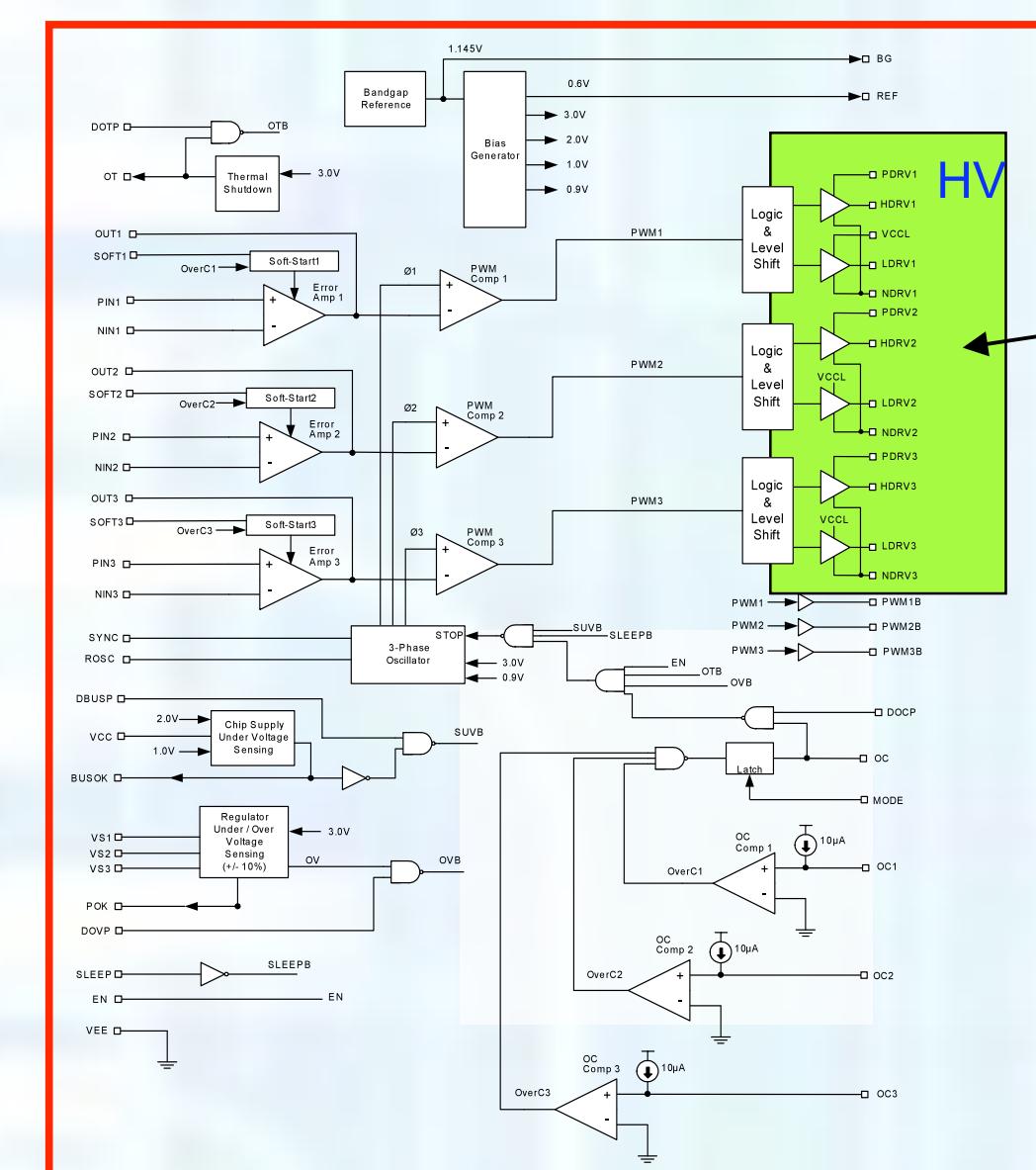


Simulations were used to optimize drain extension process and design parameters



Approach (cont.)

Rad-Hard HVCmos Controller IC

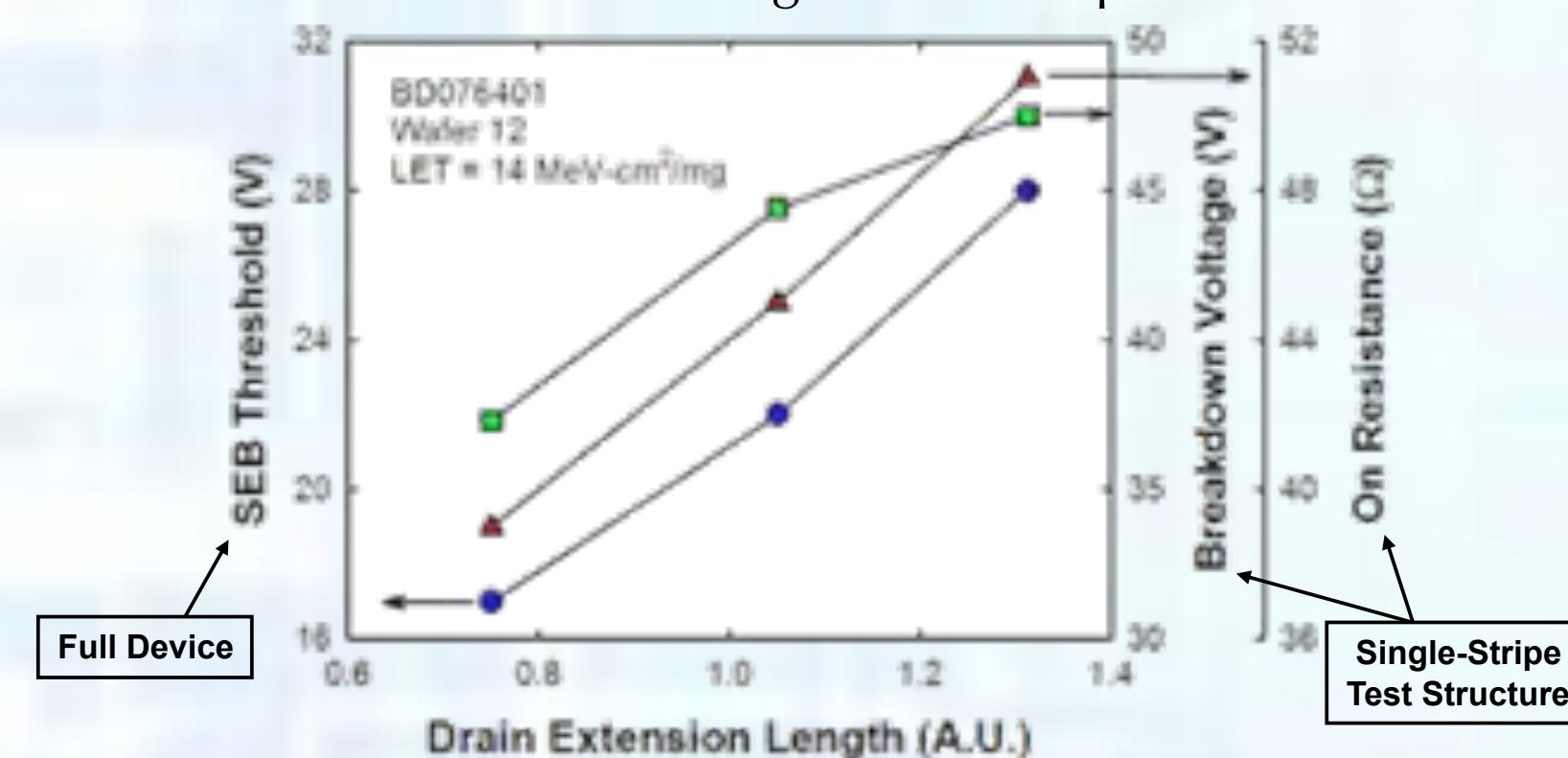


Primary goals are to develop devices with 20+ volt breakdown and dual gate technology within the CMOS7 platform

Results

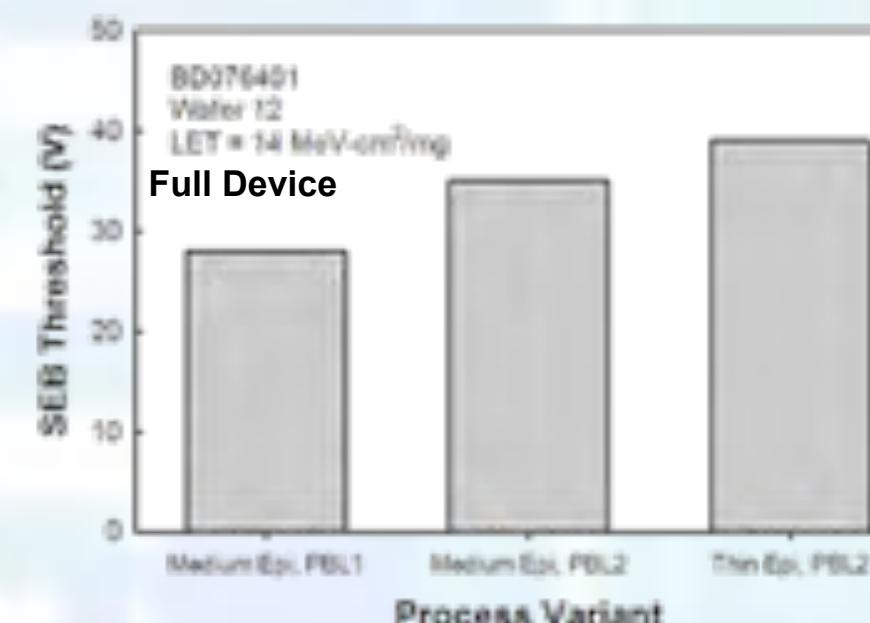
Rad-Hard Power FET

New Devices Show Improved SEB Threshold and Illustrate Design Tradeoff Space

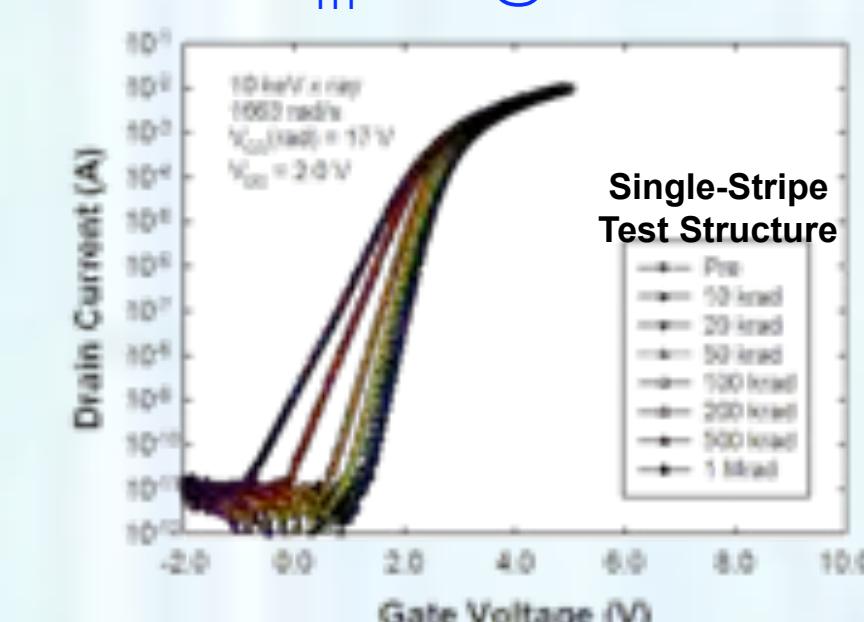


SEB threshold in original devices for an LET of 14 MeV·cm²/mg was only ~12 V.

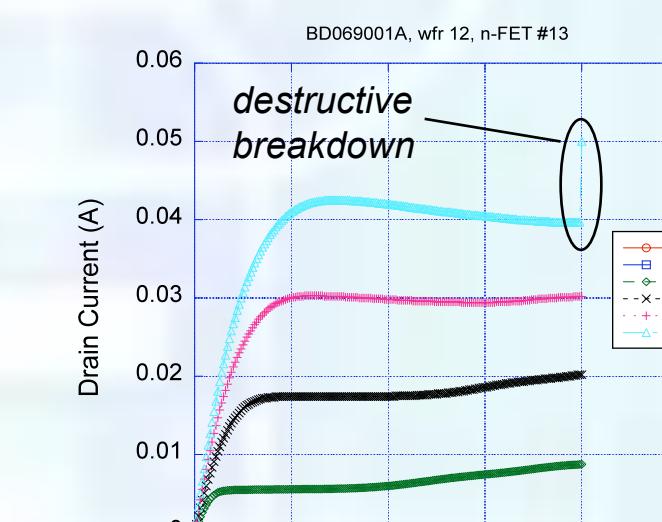
Process changes to starting material and buried layer implant improve SEB



Total-dose Results: $\Delta V_{TH} < 1V$ @ 500krad



High Voltage (HV) CMOS SOI Development



- Newest N-FETs achieve $BV_{DSS} > 40V$, newest P-FETs > 30V
- Highest breakdown voltage SOI devices ever made at the MDL!
- First co-processed SOI HV complementary (N & P) FETs at the MDL!

Significance

Dramatic increases in computing performance will be required for Sandia's future remote sensing work. Distributed power and point-of-load power conversion will be essential to meet the requirements of the improved highly integrated, low-voltage digital processing components.